

control electronics operably coupled to said imaging device for controlling reading by said readout devices and processing output from said readout devices; and

A3
Cont. an image processor responsive to processed output from said control electronics for generating an image therefrom.

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19. (Once Amended) A method of manufacturing an imaging device comprising a detector semiconductor substrate including an array of detector cells for generating charge in response to incident radiation and a readout semiconductor substrate including an array of readout cells, one of said detector cells and one of said readout cells forming an image cell, said method comprising:

G4 applying low temperature solder bumps comprising lead-tin based solder having a melting point below that of eutectic lead-tin solder to one of said substrates at positions corresponding to said image cells;

aligning respective readout and detector cells to each other; and connecting said detector and said readout cells by the application of heat to said low temperature solder bumps.

REMARKS

The Office Action mailed on December 28, 1998 has been carefully reviewed and the following remarks are made in response thereto. Claim 5 has been canceled; independent claims 1, 14, and 19 have been amended. No claims have been added. Thus, claims 1-4 and 6-31 are presently pending.

The Examiner has taken the following actions:

rejected claims 1-31 as being indefinite under 35 U.S.C. § 112, first paragraph;

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